

Title (en)  
HALF-BRIDGE SUBASSEMBLY

Title (de)  
HALBBRÜCKENBAUGRUPPE

Title (fr)  
COMPOSANTS DEMI-PONT

Publication  
**EP 1293032 A1 20030319 (DE)**

Application  
**EP 01943515 A 20010615**

Priority  

- DE 10030875 A 20000623
- EP 0106817 W 20010615

Abstract (en)  
[origin: WO0199266A1] A half-bridge subassembly used to switch electric power, wherein at least two semiconductor switches are series connected, forming a half-bridge. Each semiconductor switch has a control input; the first semiconductor switch has a first power connection which can be connected to a high voltage potential; the second semiconductor switch has a second power connection which can be connected to a low voltage potential; a second power connection of the first semiconductor switch is connected to a first power connection of the respectively second semiconductor switch; each semiconductor switch has a free-wheeling diode which is disposed in a parallel position with respect to the two power connections of the respective semiconductor switch; a Schottky diode is mounted parallel to each free-wheeling diode. The free-wheeling diode of each semiconductor switch and each Schottky diode are connected in a heat conducting manner to a heat sink, the dimensions of the thermal resistance between each Schottky diode and the heat sink being larger than the dimensions of the thermal resistance between each free-wheeling diode and the heat sink.

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**H02M 7/00**

IPC 8 full level  
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Citation (search report)  
See references of WO 0199266A1

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